

# PRODUCT / PROCESS CHANGE INFORMATION

### IMPROVED PACKING for all EEPROM in WLCSP

#### What is the change?

The packing of the **EEPROM** in **WLCSP** has been improved by adding:

- EPE protector foam (Fig. 1)
- Moisture barrier bag (MBB) with desiccant and humidity indicator (Fig. 2)
- Two bubble wrap sheets (Fig. 3)



EPE protector foam Fig. 1



Reel in M8B (no vacuum sealing)





Bubble wrap sheets



#### Why?

The new packing will improve resistance to mechanical and environmental stresses during transportation.

#### When?

The production of the WLCSP with the improved packing will start from end of October.

#### How will the change be qualified?

The improved packing has been qualified using the standard ST Microelectronics Corporate Procedures for Quality & Reliability.

#### What is the impact of the change?

- Form: Added bubble wrap sheets, Moisture barrier bag, desiccant, humidity indicator, EPE protector foam

- Fit: N/A

- Function: N/A

#### How can the change be seen?

At customer unpacking step.

## Appendix A- Product Change Information

Product family / Commercial products:	All EEPROM in WLCSP	
Customer(s):	All	
Type of change:	Packing	
Reason for the change:	<ul> <li>Will improve resistance to mechanical and environmental stresses during transportation</li> <li>Adding EPE protector foam, 2 bubble wrap sheets and a moisture barrier bag with desiccant and humidity indicator.</li> </ul>	
Description of the change:		
Notification to customer:	Week 44 / 2015	
Estimated date of first shipment:	Week 44 / 2015 (start of deployment)	

#### **Appendix B- Concerned products**

M24128-BFCS6TP/A M24128-DFCS6TP/K M24128S-FCU6T/T M24128S-FCU6T/TF M24C16-DFCU6TP/K M24C32S-FCU6T/T M24C64-DFCT6TP/K M24C64-FCS6TP/K M24C64S-FCU6T/T M24C64S-FCU6T/TF M24M01-DFCS6TP/K M24M01-RCS6TP/A M24M02-DRCS6TP/K M95128-DFCS6TP/K M95640-DFCT6TP/K M95M01-DFCS6TP/K M95M01-RCS6TP/A M95M02-DRCS6TP/K M24256-BRCS6TP/A M24256-DFCS6TP/K M24512-DFCS6TP/K M24C08-FCS5TP/S M24C08-FCT5TP/S M24C16-FCS5TP/S M95160-RCS6TP/S M95256-DFCS6TP/K M95256-RCS6TP/A M95512-DFCS6TP/K

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Date	Rev.	Description of the Revision	
October 22, 2015	1.00	First draft creation	

Source Documents & Reference Documents				
Source document Title	Rev.:	Date:		